



H1  
SJ-5303 (CLEAR)

H2  
SJ-5303 (CLEAR)



PCB Number: TIDA-00703  
PCB Rev: E1

PCB  
LOGO  
Texas Instruments

PCB  
LOGO  
Pb-Free Symbol

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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